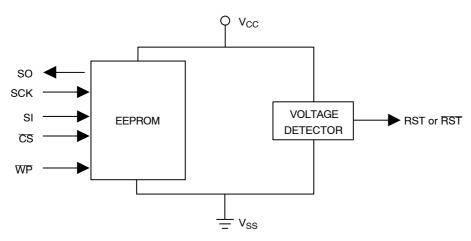
BLOCK DIAGRAM



SPECIFICATIONS

Table 1. ABSOLUTE MAXIMUM RATINGS

Parameters	Ratings	Units
Storage Temperature	-65 to +150	°C
Voltage on Any Pin with Respect to Ground (Note 1)	-0.5 to +6.5	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 2. RELIABILITY CHARACTERISTICS (Note 2)

Symbol	Parameter	Min	Units
NEND (Note 3)	Endurance	1,000,000	Program/ Erase Cycles
TDR	Data Retention	100	Years

These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

Table 3. D.C. OPERATING CHARACTERISTICS

 V_{CC} = +2.5 V to +5.5 V, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
I _{CC}	Supply Current	Read or Write at 10 MHz, SO open			2	mA
I _{SB}	Standby Current	V_{CC} < 5.5 V; V_{IN} = V_{SS} or V_{CC} , \overline{CS} = V_{CC}		12	25	μΑ
		V_{CC} < 3.6 V; V_{IN} = V_{SS} or V_{CC} , \overline{CS} = V_{CC}		10	20	
ΙL	I/O Pin Leakage	Pin at GND or V _{CC}			2	μΑ
V _{IL}	Input Low Voltage		-0.5		0.3 V _{CC}	V
V _{IH}	Input High Voltage		0.7 V _{CC}		V _{CC} + 0.5	V
V _{OL}	Output Low Voltage	$V_{CC} \ge 2.5 \text{ V}, I_{OL} = 3.0 \text{ mA}$			0.4	V
V _{OH}	Output High Voltage	$V_{CC} \ge 2.5 \text{ V}, I_{OH} = -1.6 \text{ mA}$	V _{CC} - 0.8			V

^{1.} The DC input voltage on any pin should not be lower than -0.5 V or higher than $V_{CC} + 0.5$ V. During transitions, the voltage on any pin may undershoot to no less than -1.5 V or overshoot to no more than $V_{CC} + 1.5$ V, for periods of less than 20 ns.

^{3.} Page Mode, V_{CC} = 5 V, 25°C

Table 4. A.C. CHARACTERISTICS (MEMORY) (Note 1)

 V_{CC} = 2.5 V to 5.5 V, T_A = -40°C to 85°C, unless otherwise specified.

Symbol	Parameter	Min	Max	Units
f _{SCK}	Clock Frequency	DC	10	MHz
t _{SU}	Data Setup Time	20		ns
t _H	Data Hold Time	20		ns
t _{WH}	SCK High Time	40		ns
t _{WL}	SCK Low Time	40		ns
t _{LZ}	HOLD to Output Low Z		25	ns
t _{RI} (Note 2)	Input Rise Time		2	μs
t _{FI} (Note 2)	Input Fall Time		2	μs
t _{HD}	HOLD Setup Time	0		ns
t _{CD}	HOLD Hold Time	10		ns
t _V	Output Valid from Clock Low		40	ns
t _{HO}	Output Hold Time	0		ns
t _{DIS}	Output Disable Time		20	ns
t _{HZ}	HOLD to Output High Z		25	ns
t _{CS}	CS High Time	15		ns
t _{CSS}	CS Setup Time	15		ns
t _{CSH}	CS Hold Time	15		ns
t _{WPS}	WP Setup Time	10		ns
t _{WPH}	WP Hold Time	10		ns
t _{WC} (Note 4)	Write Cycle Time		5	ms
t _{PU} (Notes 2 & 3)	Power-up to Ready Mode		1	ms

Table 5. A.C. TEST CONDITIONS

Parameter	Test Conditions
Input Rise and Fall Times	≤10 ns
Input Levels	0.3 V _{CC} to 0.7 V _{CC}
Timing Reference Levels	0.5 V _{CC}
Output Load	Current Source: I _{OL} max/ I _{OH} max; C _L = 50 pF

Test conditions according to "A.C. Test Conditions" table.
 Tested initially and after a design or process change that affects this parameter.
 t_{PU} is the delay between the time V_{CC} is stable and the device is ready to accept commands.
 t_{WC} is the time from the rising edge of CS after a valid write sequence to the end of the internal write cycle.

Table 6. ELECTRICAL CHARACTERISTICS (SUPERVISORY FUNCTION)

 $V_{CC} = Full\ range,\ T_A = -40^{\circ}C\ to\ +85^{\circ}C\ unless\ otherwise\ noted.\ Typical\ values\ at\ T_A = +25^{\circ}C\ and\ V_{CC} = 5\ V\ for\ L/M/J\ versions,$ V_{CC} = 3.3 V for T/S versions, V_{CC} = 3 V for R version and V_{CC} = 2.5 V for Z version.

Parameter	Threshold	Conditions	Min	Тур	Max	Units
Reset Threshold	L	T _A = +25°C	4.56	4.63	4.70	V
voitage		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	4.50		4.75	
	М	T _A = +25°C	4.31	4.38	4.45	
		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	4.25		4.50	
	J	T _A = +25°C	3.93	4.00	4.06	
		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	3.89		4.10	
	Т	T _A = +25°C	3.04	3.08	3.11	
		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	3.00		3.15	
	S	T _A = +25°C	2.89	2.93	2.96	
		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	2.85		3.00	
	R	T _A = +25°C	2.59	2.63	2.66	
		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	2.55		2.70	
	Z	T _A = +25°C	2.28	2.32	2.35	
		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	2.25		2.38	
Parame	ter	Conditions	Min	Typ (Note 1)	Max	Units
Reset Threshold	Гетрсо			30		ppm/°C
V _{CC} to Reset Dela	y (Note 2)	V _{CC} = V _{TH} to (V _{TH} -100 mV)		20		μs
Reset Active Time	out Period	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	140	240	460	ms
(Push-pull, Active		V _{CC} = V _{TH} min, I _{SINK} = 1.2 mA R/S/T/Z			0.3	V
CAT150xx9)		V _{CC} = V _{TH} min, I _{SINK} = 3.2 mA J/L/M			0.4	
		V _{CC} > 1.0 V, I _{SINK} = 50 μA			0.3	
(Push-pull, Active		$V_{CC} = V_{TH}$ max, $I_{SOURCE} = -500 \mu A$ R/S/T/Z	0.8 V _{CC}			V
CAT150xx9)		$V_{CC} = V_{TH}$ max, $I_{SOURCE} = -800 \mu A$ J/L/M	V _{CC} – 1.5			
(Push-pull, Active HIGH,		$V_{CC} > V_{TH}$ max, $I_{SINK} = 1.2$ mA R/S/T/Z			0.3	V
CAT ISUXXI)		V _{CC} > V _{TH} max, I _{SINK} = 3.2 mA J/L/M			0.4	
		1.8 V < $V_{CC} \le V_{TH}$ min, I _{SOURCE} = -150 μ A	0.8 V _{CC}			V
	Reset Threshold Voltage Parame Reset Threshold To VCC to Reset Delate Reset Active Times RESET Output Vo (Push-pull, Active CAT150xx9) RESET Output Vo (Push-pull, Active CAT150xx1) RESET Output Vo (Push-pull, Active CAT150xx1)	Reset Threshold Voltage M J T S R Parameter Reset Threshold Tempco V _{CC} to Reset Delay (Note 2) Reset Active Timeout Period RESET Output Voltage Low (Push-pull, Active LOW, CAT150xx9) RESET Output Voltage Low (Push-pull, Active HIGH, CAT150xx1) RESET Output Voltage Low (Push-pull, Active HIGH, CAT150xx1)	$\begin{tabular}{l l l l l l l l l l l l l l l l l l l $	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Reset Threshold Voltage	Reset Threshold Voltage

Production testing done at T_A = +25°C; limits over temperature guaranteed by design only.
 RESET output for the CAT150xx9; RESET output for the CAT150xx1.

PIN DESCRIPTION

RESET/RESET: Reset output is available in two versions: CMOS Active Low (CAT150xx9) and CMOS Active High (CAT150xx1). Both versions are push–pull outputs for high efficiency.

SI: The serial data input pin accepts op-codes, addresses and data. In SPI modes (0,0) and (1,1) input data is latched on the rising edge of the SCK clock input.

SO: The serial data output pin is used to transfer data out of the device. In SPI modes (0,0) and (1,1) data is shifted out on the falling edge of the SCK clock.

SCK: The serial clock input pin accepts the clock provided by the host and used for synchronizing communication between host and CAT15008/16.

 $\overline{\text{CS}}$: The chip select input pin is used to enable/disable the CAT15008/16. When $\overline{\text{CS}}$ is high, the SO output is tri-stated (high impedance) and the device is in Standby Mode (unless an internal write operation is in progress). <u>Every communication session between host and CAT15008/16 must be preceded by a high to low transition and concluded with a low to high transition of the $\overline{\text{CS}}$ input.</u>

 $\overline{\mathbf{WP}}$: The write protect input pin will allow all write operations to the device when held high. When $\overline{\mathbf{WP}}$ pin is tied low and the WPEN bit in the Status Register (refer to Status Register description, later in this Data Sheet) is set to "1", writing to the Status Register is disabled.

DEVICE OPERATION

The CAT15008/16 products combine the accurate voltage monitoring capabilities of a standalone voltage supervisor

with the high quality and reliability of standard EEPROMs from ON Semiconductor.

RESET CONTROLLER DESCRIPTION

The reset signal is asserted LOW for the CAT150xx9 and HIGH for the CAT150xx1 when the power supply voltage falls below the threshold trip voltage and remains asserted for at least 140 ms (t_{PURST}) after the power supply voltage has risen above the threshold. Reset output timing is shown in Figure 2.

The CAT15008/16 devices protect μPs against brown-out failure. Short duration V_{CC} transients of 4 μsec or less and 100 mV amplitude typically do not generate a Reset pulse.

Figure 1 shows the maximum pulse duration of negative–going V_{CC} transients that do not cause a reset condition. As the amplitude of the transient goes further below the threshold (increasing $V_{TH}-V_{CC}$), the maximum pulse duration decreases. In this test, the V_{CC} starts from an initial voltage of 0.5 V above the threshold and drops below it by the amplitude of the overdrive voltage ($V_{TH}-V_{CC}$).

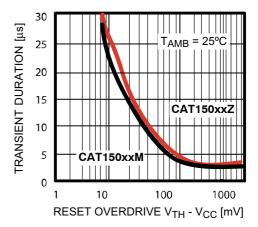


Figure 1. Maximum Transient Duration without Causing a Reset Pulse vs. Overdrive Voltage

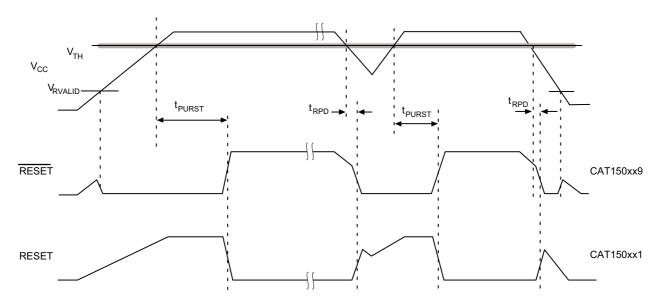


Figure 2. RESET Output Timing

EMBEDDED EEPROM DESCRIPTION

The CAT15008/16 devices support the Serial Peripheral Interface (SPI) bus protocol, modes (0,0) and (1,1). The device contains an 8-bit instruction register. The instruction set and associated op-codes are listed in Table 7.

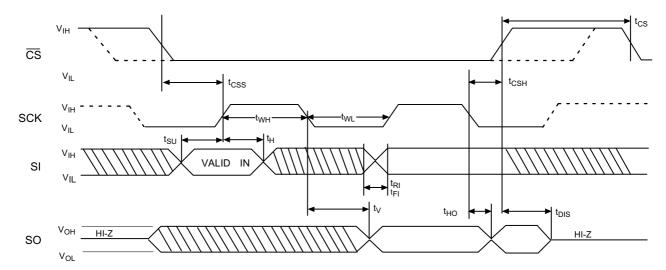
Reading data stored in the CAT15008/16 is accomplished by simply providing the READ command and an address. Writing to the CAT15008/16, in addition to a WRITE command, address and data, also requires enabling the device for writing by first setting certain bits in a Status Register, as will be explained later.

After a high to low transition on the $\overline{\text{CS}}$ input pin, the CAT15008/16 will accept any one of the six instruction op-codes listed in Table 7 and will ignore all other possible

8-bit combinations. The communication protocol follows the timing from Figure 3.

Table 7. INSTRUCTION SET

Instruction	Opcode	Operation	
WREN	0000 0110	Enable Write Operations	
WRDI	0000 0100	Disable Write Operations	
RDSR	0000 0101	Read Status Register	
WRSR	0000 0001	Write Status Register	
READ	0000 0011	Read Data from Memory	
WRITE	0000 0010	Write Data to Memory	



Note: Dashed Line = mode (1, 1)----

Figure 3. Synchronous Data Timing

STATUS REGISTER

The Status Register, as shown in Table 8, contains a number of status and control bits.

The RDY (Ready) bit indicates whether the device is busy with a write operation. This bit is automatically set to 1 during an internal write cycle, and reset to 0 when the device is ready to accept commands. For the host, this bit is read only.

The WEL (Write Enable Latch) bit is set/reset by the WREN/WRDI commands. When set to 1, the device is in a Write Enable state and when set to 0, the device is in a Write Disable state.

The BP0 and BP1 (Block Protect) bits determine which blocks are currently write protected. They are set by the user with the WRSR command and are non-volatile. The user is

allowed to protect a quarter, one half or the entire memory, by setting these bits according to Table 9. The protected blocks then become read—only.

The WPEN (Write Protect Enable) bit acts as an enable for the \overline{WP} pin. Hardware write protection is enabled when the \overline{WP} pin is low and the WPEN bit is 1. This condition prevents writing to the status register and to the block protected sections of memory. While hardware write protection is active, only the non-block protected memory can be written. Hardware write protection is disabled when the \overline{WP} pin is high or the WPEN bit is 0. The WPEN bit, \overline{WP} pin and WEL bit combine to either permit or inhibit Write operations, as detailed in Table 10.

Table 8. STATUS REGISTER

7	6	5	4	3	2	1	0
WPEN	0	0	0	BP1	BP0	WEL	RDY

Table 9. BLOCK PROTECTION BITS

Status R	egister Bits		
BP1	BP0	Array Address Protected	Protection
0	0	None	No Protection
0	1	15008: 0300-03FF	Quarter Array Protection
		15016: 0600-07FF	
1	0	15008: 0200-03FF	Half Array Protection
		15016: 0400-07FF	
1	1	15008: 0000-03FF	Full Array Protection
		15016: 0000-07FF	

Table 10. WRITE PROTECT ENABLE OPERATION

WPEN	WP	WEL	Protected Blocks	Unprotected Blocks	Status Register
0	Х	0	Protected	Protected	Protected
0	Х	1	Protected	Writable	Writable
1	Low	0	Protected	Protected	Protected
1	Low	1	Protected	Writable	Protected
Х	High	0	Protected	Protected	Protected
X	High	1	Protected	Writable	Writable

WRITE OPERATIONS

The CAT15008/16 device powers up into a write disable state. The device contains a Write Enable Latch (WEL) which must be set before attempting to write to the memory array or to the status register. In addition, the address of the memory location(s) to be written must be outside the protected area, as defined by BP0 and BP1 bits from the status register.

Write Enable and Write Disable

The internal Write Enable Latch and the corresponding Status Register WEL bit are set by sending the WREN

instruction to the CAT15008/16. Care must be taken to take the $\overline{\text{CS}}$ input high after the WREN instruction, as otherwise the Write Enable Latch will not be properly set. WREN timing is illustrated in Figure 4. The WREN instruction must be sent prior any WRITE or WRSR instruction.

The internal write enable latch is reset by sending the WRDI instruction as shown in Figure 5. Disabling write operations by resetting the WEL bit, will protect the device against inadvertent writes.

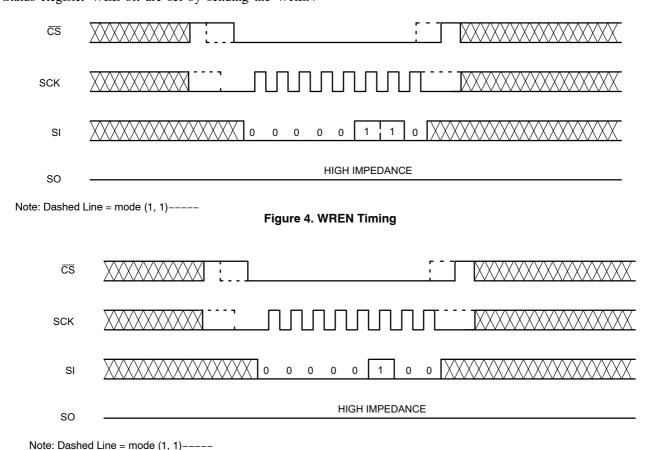


Figure 5. WRDI Timing

Byte Write

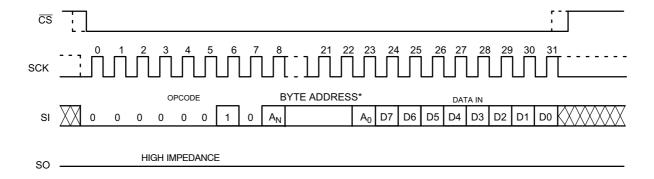
Once the WEL bit is set, the user may execute a write sequence, by sending a WRITE instruction, a 16-bit address and data as shown in Figure 6. Only 10 significant address bits are used by the CAT15008 and 11 by the CAT15016. The rest are don't care bits, as shown in Table 11. Internal programming will start after the low to high $\overline{\text{CS}}$ transition. During an internal write cycle, all commands, except for RDSR (Read Status Register) will be ignored. The $\overline{\text{RDY}}$ bit will indicate if the internal write cycle is in progress $(\overline{\text{RDY}} \text{ high})$, or the device is ready to accept commands $(\overline{\text{RDY}} \text{ low})$.

Page Write

After sending the first data byte to the CAT15008/16, the host may continue sending data, up to a total of 32 bytes, according to timing shown in Figure 7. After each data byte, the lower order address bits are automatically incremented, while the higher order address bits (page address) remain unchanged. If during this process the end of page is exceeded, then loading will "roll over" to the first byte in the page, thus possibly overwriting previously loaded data. Following completion of the write cycle, the CAT15008/16 is automatically returned to the write disable state.

Table 11. BYTE ADDRESS

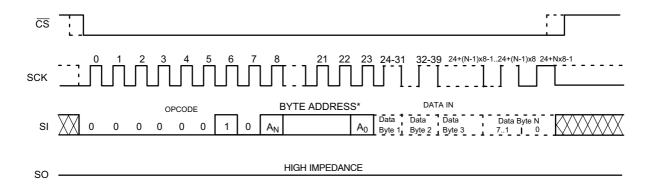
Device	Address Significant Bits	Address Don't Care Bits	# Address Clock Pulse
CAT15008	A9 – A0	A15 – A10	16
CAT15016	A10 – A0	A15 – A11	16



Notes: * Please check the Byte Address Table (Table 11)

Dashed Line = mode (1, 1)----

Figure 6. Byte WRITE Timing



Notes: * Please check the Byte Address Table (Table 11)

Dashed Line = mode (1, 1)-----

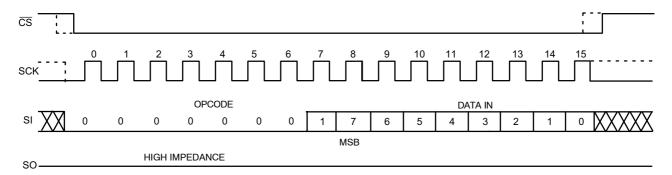
Figure 7. Page WRITE Timing

Write Status Register

The Status Register is written by sending a WRSR instruction according to timing shown in Figure 8. Only bits 2, 3 and 7 can be written using the WRSR command.

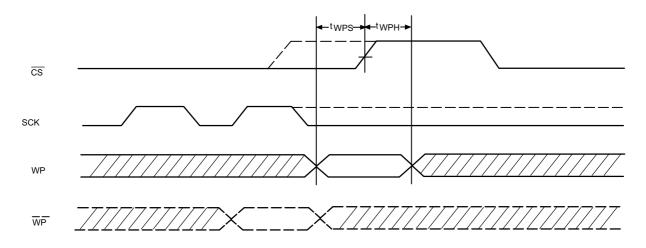
Write Protection

The Write Protect (\overline{WP}) pin can be used to protect the Block Protect bits BP0 and BP1 against being inadvertently altered. When \overline{WP} is low and the WPEN bit is set to "1", write operations to the Status Register are inhibited. \overline{WP} going low while \overline{CS} is still low will interrupt a write to the status register. If the internal write cycle has already been initiated, \overline{WP} going low will have no effect on any write operation to the Status Register. The \overline{WP} pin function is blocked when the WPEN bit is set to "0". The \overline{WP} input timing is shown in Figure 9.



Note: Dashed Line = mode (1, 1)----

Figure 8. WRSR Timing



Note: Dashed Line = mode (1, 1)----

Figure 9. WP Timing

READ OPERATIONS

Read from Memory Array

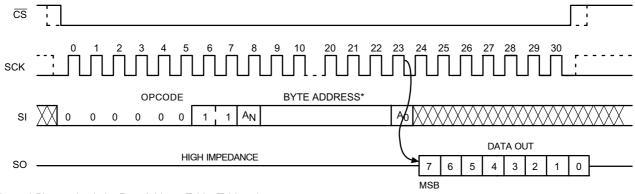
To read from memory, the host sends a READ instruction followed by an 16-bit address (see Table 11 for the number of significant address bits).

After receiving the last address bit, the CAT15008/16 will respond by shifting out data on the SO pin (as shown in Figure 10). Sequentially stored data can be read out by simply continuing to run the clock. The internal address pointer is automatically incremented to the next higher address as data is shifted out. After reaching the highest memory address, the address counter "rolls over" to the

lowest memory address, and the read cycle can be continued indefinitely. The read operation is terminated by taking \overline{CS} high.

Read Status Register

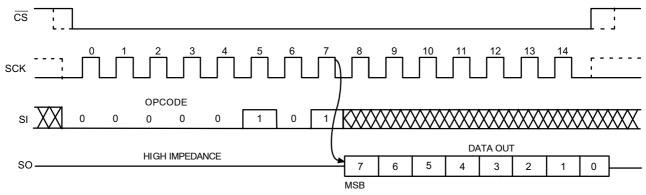
To read the status register, the host simply sends a RDSR command. After receiving the last bit of the command, the CAT15008/16 will shift out the contents of the status register on the SO pin (Figure 11). The status register may be read at any time, including during an internal write cycle.



Notes: * Please check the Byte Address Table (Table 11)

Dashed Line = mode (1, 1)-----

Figure 10. READ Timing



Note: Dashed Line = mode (1, 1)----

Figure 11. RDSR Timing

ORDERING INFORMATION

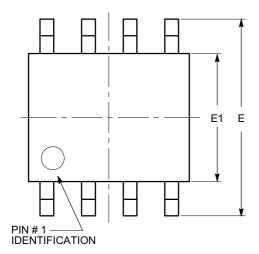
Orderable Part Numbers - CAT150xx Series (See Notes 1 - 4)							
Device	Package-Pins	Shipping					
CAT150089SWI-GT3	2.85 to 3.00 V		3000 Tape & Reel				
CAT150089SWI-G	2.85 to 3.00 V		100 Tube				
CAT150161MWI-GT3	4.25 to 4.50 V	SOIC-8					
CAT150169MWI-GT3	4.25 to 4.50 V		3000 Tape & Reel				
CAT150169SWI-GT3	2.85 to 3.00 V						

- All packages are RoHS-compliant (Lead-free, Halogen-free).
 The standard lead finish is NiPdAu pre-plated (PPF) lead frames.
 For additional package and temperature options, please contact your nearest ON Semiconductor Sales office.

 4. For detailed information and a breakdown of device nomenclature and numbering
- systems, please see the ON Semiconductor Device Nomenclature document, TND310/D, available at www.onsemi.com

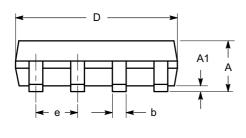
PACKAGE DIMENSIONS

SOIC 8, 150 mils CASE 751BD-01 ISSUE O

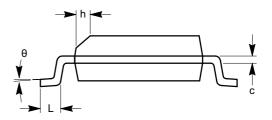


SYMBOL	MIN	NOM	MAX
Α	1.35		1.75
A1	0.10		0.25
b	0.33		0.51
С	0.19		0.25
D	4.80		5.00
Е	5.80		6.20
E1	3.80		4.00
е	1.27 BSC		
h	0.25		0.50
L	0.40		1.27
θ	0°		8°

TOP VIEW



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-012.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada

Fax: 303-675-2176 or 800-344-3860 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

CAT15008/D